



# 1<sup>st</sup> BUILD-UP SUBSTRATE SYMPOSIUM

In person event

May 2, 2024

SEMI, 673 S. Milpitas Blvd

Milpitas, CA 95035



**IEEE  
ELECTRONICS  
PACKAGING  
SOCIETY**

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DAY 1 Program  
 May 2nd, 2024  
 at  
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May 2nd	Schedule	Speakers	Affiliation	Talk Title
Opening	8:30am	Habib Hichri	Ajinomoto	Opening and BUSS program
Keynote I	8:45am	Daniel Burger	NAPMP, Associate Director	Keynote:NAPMP Plans & Advanced Substrate Onshoring
Keynote II	9:30am	D.C. Hu	SiPlus, Founder	2.XD Integrated Substrate Solutions for High Performance Computing
	10:15am	<i>Tea Break</i>		
Substrate Manufacturing & Onshoring (Chair: Rozalia Beica)	11:00am	Sundar Kamath	Sanmina	An American PCB Manufacturer's Perspective on the Domestic Substrates Manufacturing Opportunity
	11:20am	Meredith LaBeau	Calumet, CTO	Onshoring Organic Substrates (High-Density Build-Ups):A tale of Domestic Manufacturing & Title 3 Investments
	11:40am	Sung Jin Kim	Absolics, CTO	Packaging Substrate Solutions for Advanced Packaging Requirements
	12:00pm	Michael Gleason	Green Source	
	12:20pm	<i>Lunch from Dish Dash</i>		
Materials Advances for Substrates (Chair: Annette Teng)	1:30pm	Yishio Nishimura	Ajinomoto	Advanced Insulating Material for Next Generation Packaging
	1:50pm	Yuta Ogawa	TaiyoInk	Taiyo's Photo-Dielectric for High Density Substrate Applications
	2:10pm	Fukui Masato	Resonac	Substrate Materials for Advanced Packaging
	2:30pm	Hikaru Mizuno	JSR Micro	Novel Low Loss Materials for Advanced IC Packaging
Emerging Substrate Technologies (Chair: Steven Verhaverbeke)	2:50pm	Steven Verhaverbeke	AMAT	Wafer Level Substrates – An Emerging New Technology
	3:10pm	Farhang Yazdani	BroadPak	Advanced X64 UCle Interface Implementatio on a Substrate
	3:30pm	Ken Yang, Vineeth Harish	UCLA	Chiplet Integration on Organic Buildup with Silicon Interconnect Fabric
	3:50pm	<i>Tea Break</i>		
“Substrate Needs: User Perspective” Panel session moderated by Jan Vardaman	4:30pm	Sai Boyapati	AMD, Sr. Dir. Adv. Pkg.	<b>Substrate Needs: The User Perspective</b>
		<a href="#">Diane Peng</a>	Marvell	
		<a href="#">Omar Bchir</a>	Qualcomm	
		<a href="#">Susan Bagen</a>	Raytheon, Microelectronics Cslt.	
		Jon Woodyard	Microsoft, Principal Engineer	
	5:30pm	<i>Barbecue Dinner catered by Armadillo Willy's</i>		





DAY 2 Program  
 May 3rd, 2024  
 at  
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May 3rd Friday	Schedule	Speakers	Affiliation	Talk Title
Keynote I	9:00am	Venky Sundaram	3 D System Scaling, Founder	USA Landscape for Substrate Manufacturing
Keynote II	9:35am	Rahul Iyer	KCK Group	Venture Funding for startups
	10:10am	30 minutes Tea break		
Panel Equipment for Substrates (Chair Kuldip Johal)	10:40am	Kyle Baker	MKS Instruments	QCW CO2 laser drilling for FCBGA applications.
	11:00am	Takuma Yoshikawa	Nikko Materials	The Latest Vacuum Lamination Challenges and Technology
	11:20am	Frank Bruening	MSD-Atotech	Systems solutions for Advanced IC substrate manufacturing
	11:40pm	Rozalia Beica	LQDX	The Future of AI and HPC Substrates: A Breakthrough Interconnect Technology
	12:00pm	60 minutes Lunch		
Panel Equipment and Technologies for Substrates (Chair: Kuldip Johal)	1:00pm	Harish V Penmethsa	Applied Materials	Metallization Technologies for Advanced Substrates
	1:20pm	Keith Best	Onto Innovation	Challenges for Organic & Glass Core Substrates as Advanced Packaging RDL Approaches < 2 μm L/S
	1:40pm	Gustavo Ramos	Green Source Engineering	Manufacturing with Zero Liquid Discharge (ZLD)
	2:00pm	Saminda Dharmarathna	MacDermid Alpha	Advanced Electroplating Processes for IC Substrates – Redistribution Layer and Embedded Trenches
	2:20pm	Purnima Narayanan	YES	Advanced packaging metallization-Substrate interaction with catalyst & electroless deposition of Cu
	2:40pm	20 minutes Tea break		
Inspection and Testing (Chair: Farhang)	3:00pm	Robert Bishop	Beltonics	Advanced Metrology for High Density Substrates
	3:20pm		Tessolve	
	3:40pm	Orit Hava Armon Hershkovich	KLA Corporation	Inspection challenges in ICS & Advanced panel packaging markets
“Empowering Startups in Advanced Substrates: A Key Component in US Onshoring” Panel session moderated by Venky Sundaram and Kuldip Johal	4:00pm-5:00pm	Simon McElrea	LQDX	Empowering Startups in Advanced Substrates: A Key Component in US Onshoring Supply chain innovations
		Sam Salama	Hyperion	
		Tristan O. El Bouayadi	Thintronics	Empowering Startups in Advanced Substrates: A Key Component in US Onshoring Substrate and Design Innovations
		Siddharth Ravichandran	Chiptetz	
		Brett Sawyer	Nubis Communications	
Michael Gleason	Greensource			
Closing Remarks	5:00pm	Habib Hichri		



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